



10ns, Rail-to-Rail, High-Speed Comparator

1 FEATURES

- High Speed: 10ns
- Rail-to-Rail I/O
- Supply Voltage: 2.7 V to 5.5 V
- Push-Pull CMOS Output Stage
- Shutdown (RS8931S Only)
- Micro Packages: SOT23-5, SOP8, SOT23-6
- Low Supply Current: 2.5mA

2 APPLICATIONS

- Automatic Test Equipment
- Wireless Base Stations
- Threshold Detectors
- Zero-Crossing Detectors
- Window Comparators

3 DESCRIPTIONS

The RS893X family of push-pull output comparators feature a fast 10ns propagation delay and operation from 2.7 V to 5.5 V. Beyond-the-rails input common-mode range makes it an ideal choice for low-voltage applications. The rail-to-rail output directly drives either CMOS or TTL logic.

Microsize packages provide options for portable and space-restricted applications. The RS8931 is available in SOT23-5 package. The RS8932 is available in SOP8 packages. The RS8931S is available in SOT23-6 package.

Device Information (1)							
PACKAGE	BODY SIZE (NOM)						
SOT23-5	2.90mm×1.60mm						
SOP8	4.90mm×3.90mm						
SOT23-6	2.90mm×1.60mm						
	PACKAGE SOT23-5 SOP8						

Device Information ⁽¹⁾

(1) For all available packages, see the orderable addendum at the end of the data sheet.



Table of Contents

1 FEATURES	
2 APPLICATIONS	1
3 DESCRIPTIONS	1
4 REVISION HISTORY	
5 PACKAGE/ORDERING INFORMATION ⁽¹⁾	4
6 PIN CONFIGURATION AND FUNCTIONS (TOP VIEW)	5
7 SPECIFICATIONS	6
7.1 Absolute Maximum Ratings	6
7.2 ESD Ratings	6
7.3 Recommended Operating Conditions	6
7.4 Electrical Characteristics	7
7.5 Switching Characteristics	
7.6 Typical Characteristics	9
8 DETAILED DESCRIPTION	
8.1 Overview	11
8.2 Functional Block Diagram	11
8.3 Feature Description	
8.3.1 Operating Voltage	
8.3.2 Input Overvoltage Protection	
8.4 Device Functional Modes	
8.4.1 Shutdown	
9 APPLICATION AND IMPLEMENTATION	
9.1 Application Information	
9.1.1 Adding External Hysteresis	
9.2 Typical Application	
9.2.1 Relaxation Oscillator	
10 POWER SUPPLY RECOMMENDATIONS	
11 LAYOUT	
11.1 Layout Guidelines	
11.2 Layout Example	15
12 PACKAGE OUTLINE DIMENSIONS	
13 TAPE AND REEL INFORMATION	



4 REVISION HISTORY

Note: Page numbers for previous revisions may different from page numbers in the current version.

VERSION	Change Date	Change Item
A.0	2024/04/18	Preliminary version completed
A.0.1	2024/07/24	Update Electrical Characteristics
A.1	2024/09/06	 Changed the Orderable Device of RS8933 to RS8931S Update Electrical Characteristics



5 PACKAGE/ORDERING INFORMATION⁽¹⁾

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking ⁽²⁾	MSL ⁽³⁾	Package Qty
RS8931XF	SOT23-5	5	1	-40°C ~125°C	8931	MSL3	Tape and Reel, 3000
RS8932XK	SOP8	8	2	-40°C ~125°C	RS8932	MSL3	Tape and Reel, 4000
RS8931SXH	SOT23-6	6	1	-40°C ~125°C	8931S	MSL3	Tape and Reel, 3000

NOTE:

(1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.

(2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

(3) RUNIC classify the MSL level with using the common preconditioning setting in our assembly factory conforming to the JEDEC industrial standard J-STD-20F, Please align with RUNIC if your end application is quite critical to the preconditioning setting or if you have special requirement.

6 PIN CONFIGURATION AND FUNCTIONS (TOP VIEW)





Pin Description

	Р	IN	I/O ⁽¹⁾	DESCRIPTION
NAME	SOT23-5	SOT23-6	1/0 (-/	DESCRIPTION
OUT	1	5	0	Output.
-Vs	2	2	-	Negative Power Supply.
+IN	3	3	I	Non-Inverting Input.
-IN	4	1	I	Inverting Input.
+Vs	5	4	-	Positive Power Supply.
SHDN	-	6	-	Shutdown (Only for RS8931S). If this pin is floating, the device will be in idle mode. When SHDN = "low", the part is active; When SHDN = "high", the part is in shutdown.

(1) I=Input, O=Output.



Pin Description

NAME	PIN	I/O ⁽¹⁾	DESCRIPTION
INAME	SOP8		DESCRIPTION
1	+INA	I	Non-Inverting Input of Channel A.
2	-INA	I	Inverting Input of Channel A.
3	+INB	I	Non-Inverting Input of Channel B
4	-INB	I	Inverting Input of Channel B.
5	-Vs	-	Negative Power Supply.
6	OUTB	0	Output of Channel B.
7	OUTA	0	Output of Channel A.
8	+Vs	-	Positive Power Supply.
(1) I-Input	O-Output		

(1) I=Input, O=Output.



7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

			MIN	MAX	UNIT
	Supply, Vs=(V+) - (V-)			6	
Voltage	Signal input pin ⁽²⁾		(V-)-0.3	(V+)+0.3	V
	Signal output pin ⁽³⁾		(V-)-0.3	(V+)+0.3	
	Signal input pin ⁽²⁾		-10	10	mA
Current	Signal output pin ⁽³⁾		-55 55		mA
	Output short-circuit ⁽⁴⁾		Conti		
		SOT23-5		230	
ALθ	Package thermal impedance ⁽⁵⁾	SOP8		110	°C/W
	SOT			230	
	Operating range, T _A		-40	125	
Temperature	Junction, TJ ⁽⁶⁾		-40	150	°C
	Storage, T _{stg}		-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10 mA or less.

(3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.3V beyond the supply rails should be current-limited to ±55mA or less.

(4) Short-circuit to ground, one amplifier per package.

(5) The package thermal impedance is calculated in accordance with JESD-51.

(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
Maria		Human-Body Model (HBM)	±3000	V
V _(ESD) Electrostatic discharge	Charged-Device Model (CDM)	±1000	v	



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage $\lambda (z = (\lambda (z) - \lambda (z))$	Single-supply	2.7		5.5	V
Supply voltage, Vs= (V+) - (V-)	Dual-supply	±1.35		±2.75	v



7.4 Electrical Characteristics

(At $T_A = +25^{\circ}$ C, $V_S = 2.7$ V to 5.5V, Full = -40°C to +125°C, unless otherwise noted.)⁽¹⁾

				RS893X				
	PARAMETER	CONDITIONS	TEMP	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT	
Vcc	Operating Voltage Range			2.7		5.5	V	
			+25°C		2.5	4.2	•	
lq	Quiescent Current Per Amplifier	Vs=5V, no load	Full			4.5	mA	
DCDD	Device Complex Data attain Data		+25°C		80		JD	
PSRR	Power Supply Rejection Ratio	V _s = 2.7V to 5.5V	Full		70		dB	
INPUT		·						
Vos	Input offset voltage	V _{CM} =V _S /2	+25°C	-5	±1	5	mV	
$\Delta V_{OS}/\Delta T$	Input Offset Voltage Drift		Full		5		μV/°C	
	Input Hysteresis		+25°C		1.5		mV	
	Innut Dias Current (4)(5)	N _N /2	+25°C		±2	±100		
IB	Input Bias Current ⁽⁴⁾⁽⁵⁾	V _{CM} =V _S /2	Full		±12	±300	рА	
los	Input Offset Current ⁽⁴⁾	V _{CM} =V _S /2	+25°C		±12	±100	pА	
V_{CM}	Common-Mode Voltage Range		Full	(-V _s)-0.2		(+V _s)+0.2	V	
	Common Mode Rejection Ratio	$V_{s} = \pm 2.75V,$ $V_{CM} = -0.2V$ to $(+V_{s}) + 0.2V$	+25°C		75		dB	
CNADD			Full		65			
CMRR		Vs = ±1.35V, V _{CM} = -0.2V to (+Vs) + 0.2V	+25°C		65			
			Full		60			
OUTPUT								
	Output Valtage Swing from Deil		+25°C		25	40		
Voh, Vol	Output Voltage Swing from Rail	Vs=5V, I _{OUT} = ±1mA	Full			50	mV	
			+25°C	15	25			
		$V_s = 2.7V, R_L = 2\Omega$ to GND	Full	10			mA	
Ιουτ	Output Short-Circuit Current		+25°C	65	89			
		$V_s = 5.5V, R_L = 2\Omega \text{ to GND}$	Full	55				
Shutdow	n							
toff	Shutdown Turn-Off Time	Vs=5.5V	+25°C		5		ns	
ton	Shutdown Turn-On Time	Vs=5.5V	+25°C		110		ns	
	SHDN Low Threshold	Vs=2.7V to 3.6V	- II			(+V _S)-1.8	v	
VIL	Comparator is enabled	Vs=4.5V to 5.5V	Full			(+Vs)-2.3		
	SHDN High Threshold	Vs=2.7V to 3.6V	- II	(+Vs)-0.7			V	
VIH	Comparator is disabled	Vs=4.5V to 5.5V	Full	(+Vs)-0.9			V	
B(SHDN)	SHDN Input Bias Current		Full		0.01	1	μA	
I _{Q(SHDN)}	Shutdown Quiescent Current		Full		0.5	5	μA	

(1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

(4) This parameter is ensured by design and/or characterization and is not tested in production.

(5) Positive current corresponds to current flowing into the device.



7.5 Switching Characteristics

(At $T_A = +25^{\circ}C$, $V_S = \pm 2.5V$, $C_L = 15pF$, unless otherwise specified.)⁽¹⁾

	PARAMETER	CONDITIONS	TEMP	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
+ .	Dreposition Dolor Time $(4)(5)$	Overdrive =50mV	25°C		10		
t _{pd}	Propagation Delay Time ⁽⁴⁾⁽⁵⁾	Overdrive =100mV	25°C		9		
Δt _{sk}	Propagation Delay Skew ⁽⁶⁾	Overdrive =50mV	25°C		0.7		ns
t _R	Rise Time ⁽⁷⁾		25°C		2.2		
tF	Fall Time ⁽⁷⁾		25°C		2.5		

NOTE:

(1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

(4) Not production tested.

(5) Propagation delay cannot be accurately measured with low overdrive on automatic test equipment. This parameter is ensured by characterization and testing at 100 mV overdrive.

(6) The difference between the propagation delay going high and the propagation delay going low.

(7) Measured between 10% of V_s and 90% of V_s .



7.6 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^{\circ}$ C, Vs=5 V, and input overdrive = 100 mV unless otherwise noted.



Figure 1. Output Response for Various Overdrive Voltages (L-H)



Figure 3. Response to 5MHz Square Wave



Figure 5. Propagation Delay vs Capacitive Load



Figure 2. Output Response for Various Overdrive Voltages (H-L)



Figure 4. Wake-Up Delay vs Temperature







TYPICAL CHARACTERISTICS (Continued)

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^{\circ}$ C, Vs=5 V, and input overdrive = 100 mV unless otherwise noted.



Figure 7. Propagation Delay vs Input Overdrive



Figure 9. Quiescent Current vs Temperature





Figure 8. Propagation Delay vs Supply Voltage



Figure 10. Quiescent Current vs Supply Voltage





8 DETAILED DESCRIPTION

8.1 Overview

The RS893X devices both feature high-speed response and include 1.5mV of internal hysteresis for improved noise immunity with an input common-mode range that extends 0.2V beyond the power-supply rails.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Operating Voltage

The RS893X comparators are specified for use on a single supply from 2.7 V to 5.5 V (or a dual supply from ± 1.35 V to ± 2.75 V) over a temperature range of -40° C to $\pm 125^{\circ}$ C. These devices continue to function below this range, but performance is not specified.

8.3.2 Input Overvoltage Protection

Device inputs are protected by electrostatic discharge (ESD) diodes that conduct if the input voltages exceed the power supplies by more than approximately 300mV. Momentary voltages greater than 300mV beyond the power supply can be tolerated if the input current is limited to 10 mA. This limiting is easily accomplished with a small input resistor in series with the comparator, as shown in Figure 13.



Figure 13. Input Current Protection for Voltages Exceeding the Supply Voltage



8.4 Device Functional Modes

8.4.1 Shutdown

A shutdown pin allows the device to go into idle when it is not in use. When the shutdown pin is high, the device draws approximately 0.5μ A, and the output goes to high impedance. When the shutdown pin is low, the RS893X is active. When the RS893X shutdown feature is not used, connect the shutdown pin to the most negative supply, as shown in Figure 14. Exiting shutdown mode requires approximately 100ns. The RS8931 and RS8932 does not have the shutdown feature.







9 APPLICATION AND IMPLEMENTATION

Information in the following applications sections is not part of the RUNIC component specification, and RUNIC does not warrant its accuracy or completeness. RUNIC's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

9.1.1 Adding External Hysteresis

The RS893X has a robust performance when used with a good layout. However, comparator inputs have little noise immunity within the range of a specified offset voltage (±5 mV). For slow-moving or noisy input signals, the comparator output can cause an undesirable switch state as input signals move through the switching threshold. In such applications, the 1.5mV of internal hysteresis of the RS893X might not be sufficient. For greater noise immunity, external hysteresis can be added by connecting a small amount of feedback to the positive input. Figure 15 shows a typical topology used to introduce 25 mV of additional hysteresis, for a total of 1.5mV hysteresis when operating from a single 5V supply. Use Equation 1 to calculate the approximate total hysteresis.

$$V_{\rm HYST} = \frac{(V+) \times R_1}{R_1 + R_2} + 1.5 \text{mV}$$
(1)

The total hysteresis, V_{HYST} , sets the value of the transition voltage required to switch the comparator output, by enlarging the threshold region, thereby reducing sensitivity to noise.



Figure 15. Adding Hysteresis to the RS893X

9.2 Typical Application

9.2.1 Relaxation Oscillator

The RS893X can easily be configured as a simple and inexpensive relaxation oscillator. In Figure 16, the R₂ network sets the trip threshold at 1/3 and 2/3 of the supply. Because this circuit is a high-speed circuit, the resistor values are low to minimize the effects of parasitic capacitance. The positive input alternates between 1/3 of V+ and 2/3 of V+, depending on whether the output is low or high. The time to charge (or discharge) is $0.69 \times R_1C$. Therefore, the period is $1.38 \times R_1C$. For 62 pF and $1k\Omega$ as shown in Figure 16, the output is calculated to 10.9MHz. An implementation of this circuit oscillated at 9.6MHz. Parasitic capacitance and component tolerances explain the difference between theory and actual performance.





Figure 16. Relaxation Oscillator

9.2.1.1 Design Requirements

For hysteresis of 1/3 of V+ and threshold levels between 1/3 of V+ and 2/3 of V+, the resistors connected to the comparator positive input must be equal in value. The resistor value must be kept low enough so it does not create additional time constant because of the input capacitor and board parasitic capacitor. The value of the charging resistor, R_1 , must be relatively low for high-frequency switching without drawing high current and affecting the output high and low level. The value of the charging capacitor must be high enough to avoid errors cause by parasitic capacitance.

9.2.1.2 Detailed Design Procedure

For the positive input, $+IN = 1/3 V_{OUT} + 1/3 V_{+} = 1/3 V_{+}$ if V_{OUT} is low and assuming V_{OL} is very close to GND. Or, $+IN = 1/3 V_{OUT} + 1/3 V_{+} = 1/3 V_{+} = 2/3 V_{+}$ if V_{OUT} is high and assuming V_{OH} is very close to V+.

For the negative input, the capacitor charges to 2/3 V+ and discharges to 1/3 V+ exponentially at the same rate with a time constant of R₁C.



10 POWER SUPPLY RECOMMENDATIONS

The RS893X comparators are specified for use on a single supply from 2.7 V to 5.5 V (or a dual supply from ± 1.35 V to ± 2.75 V) over a temperature range of -40° C to 125° C. These devices continue to function below this range, but performance is not specified.

Place bypass capacitors close to the power-supply pins to reduce noise coupling in from noisy or high-impedance power supplies.

11 LAYOUT

11.1 Layout Guidelines

For any high-speed comparator or amplifier, proper design and printed-circuit board (PCB) layout are necessary for optimal performance. Excess stray capacitance on the active input, or improper grounding, can limit the maximum performance of high-speed circuitry.

Minimizing resistance from the signal source to the comparator input is necessary to minimize the propagation delay of the complete circuit. The source resistance, along with input and stray capacitance, creates an RC filter that delays voltage transitions at the input, and reduces the amplitude of high-frequency signals. The input capacitance of the RS893X, along with stray capacitance from an input pin to ground, results in several picofarads of capacitance.

The location and type of capacitors used for power-supply bypassing are critical to high-speed comparators. The suggested 2.2μ F tantalum capacitor does not need to be as close to the device as the 0.1μ F capacitor, and may be shared with other devices. The 2.2μ F capacitor buffers the power-supply line against ripple, and the 0.1μ F capacitor provides a charge for the comparator during high-frequency switching.

In a high-speed circuit, fast rising and falling switching transients create voltage differences across lines that would be at the same potential at DC. To reduce this effect, use a ground plane to reduce difference in voltage potential within the circuit board. A ground plane has the advantage of minimizing the effect of stray capacitances on the circuit board by providing a more desirable path for the current to flow. With a signal trace over a ground plane, at high-frequency the return current (in the ground plane) tends to flow right under the signal trace. Breaks in the ground plane (as simple as through-hole leads and vias) increase the inductance of the plane, making it less effective at higher frequencies. Breaks in the ground plane for necessary vias must be spaced randomly.

11.2 Layout Example







12 PACKAGE OUTLINE DIMENSIONS SOT23-5⁽³⁾





RECOMMENDED LAND PATTERN (Unit: mm)





Compleal	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Мах	
A ⁽¹⁾	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
с	0.100	0.200	0.004	0.008	
D ⁽¹⁾	2.820	3.020	0.111	0.119	
E ⁽¹⁾	1.500	1.700	0.059	0.067	
E1	2.650	2.950	0.104	0.116	
e	0.950 (BSC) ⁽²⁾	0.037 (BSC) ⁽²⁾		
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
θ	0°	8°	0°	8°	

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.

BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
 This drawing is subject to change without notice.



SOP8⁽³⁾





RECOMMENDED LAND PATTERN (Unit: mm)





Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Min Max		Max		
A ⁽¹⁾	1.350	1.750	0.053	0.069		
A1	0.100	0.250	0.004	0.010		
A2	1.350	1.550	0.053	0.061		
b	0.330	0.510	0.013	0.020		
с	0.170	0.250	0.007	0.010		
D ⁽¹⁾	4.800	5.000	0.189	0.197		
e	1.270(BSC) ⁽²⁾	0.050(BSC) ⁽²⁾			
E	5.800	6.200	0.228	0.244		
E1 ⁽¹⁾	3.800	4.000	0.150	0.157		
L	0.400	1.270	0.016	0.050		
θ	0°	8°	0°	8°		

NOTE:

- Plastic or metal protrusions of 0.15mm maximum per side are not included.
 BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
 This drawing is subject to change without notice.



SOT23-6⁽³⁾





RECOMMENDED LAND PATTERN (Unit: mm)





Symbol	Dimensions I	n Millimeters	Dimensions In Inches			
	Min	Max	Min	Max		
A ⁽¹⁾	1.050	1.250	0.041	0.049		
A1	0.000	0.100	0.000	0.004		
A2	1.050	1.150	0.041	0.045		
b	0.300	0.500	0.012	0.020		
С	0.100	0.200	0.004	0.008		
D ⁽¹⁾	2.820	3.020	0.111	0.119		
E ⁽¹⁾	1.500	1.700	0.059	0.067		
E1	2.650	2.950	0.104	0.116		
e	0.950(BSC) ⁽²⁾	0.037(BSC) ⁽²⁾			
e1	1.800	2.000	0.071	0.079		
L	0.300	0.600 0.012		0.024		
θ	0°	8°	0°	8°		

NOTE:

Plastic or metal protrusions of 0.15mm maximum per side are not included.
 BSC (Basic Spacing between Centers), "Basic" spacing is nominal.

3. This drawing is subject to change without notice.



13 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SOP8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
SOT23-6	7"	9.5	3.17	3.23	1.37	4.0	4.0	2.0	8.0	Q3

NOTE:

1. All dimensions are nominal.

2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

IMPORTANT NOTICE AND DISCLAIMER

Jiangsu RUNIC Technology Co., Ltd. will accurately and reliably provide technical and reliability data (including data sheets), design resources (including reference designs), application or other design advice, WEB tools, safety information and other resources, without warranty of any defect, and will not make any express or implied warranty, including but not limited to the warranty of merchantability Implied warranty that it is suitable for a specific purpose or does not infringe the intellectual property rights of any third party.

These resources are intended for skilled developers designing with RUNIC products You will be solely responsible for: (1) Selecting the appropriate products for your application; (2) Designing, validating and testing your application; (3) Ensuring your application meets applicable standards and any other safety, security or other requirements; (4) RUNIC and the RUNIC logo are registered trademarks of RUNIC INCORPORATED. All trademarks are the property of their respective owners; (5) For change details, review the revision history included in any revised document. The resources are subject to change without notice. Our company will not be liable for the use of this product and the infringement of patents or third-party intellectual property rights due to its use.